

	ТЕСЬ	INICAL DATA SH	IFFT		2/5
STRAIO		D17/	.423.243		
	rcb		•		
		Series : S	SMA-COM		
PACKAGING			<b>SPECIFICATION</b>		
Standard	Unit	Other			
100	'W' option	Contact us			
ELECTRICAL CHARACTERISTICS			<u>ENVIRONMENTAL</u>		
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	0-18 1.14 + 0,0000 0.05 - ( 100 500	Ω GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB Maxi Veff Maxi	Operating temperature -65/+165 ° C Hermetic seal NA Atm.cm3/s Panel leakage NA		
Dielectric withstanding voltage 1000		Veff mini $M\Omega$ mini	OTHERS CHARACTERISTICS		
			Assembly instruc	ction	NA
			Others :		
MECHAN	ICAL CHARACTE	<u>RISTICS</u>	-		
Center contact retent Axial force – Matin Axial force – Oppos Torque	g end 27 site end 27	N mini N mini N.cm mini			
Recommended torque Mating Panel nut	NA	N.cm N.cm			
Mating life Weight	100 1,5600	Cycles mini g			
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<b>Issue :</b> 1149 A In the effort to improve necessary.	e our products, we reserve	e the right to make ch	anges judged to be		RADIALL®

#### **TECHNICAL DATA SHEET**

## STRAIGHT JACK RECEPTACLE FOR PCB

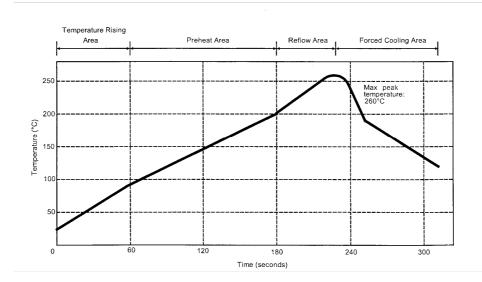
### **SMT TYPE - EDGE CARD.**

R124.423.243

Series : SMA-COM

# SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



#### **TEMPERATURE PROFILE**

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

